

## 1. General description

Hyperfast power diode in a SOD113 (2-lead TO-220F) plastic package.

## 2. Features and benefits

- Isolated plastic package
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses in associated MOSFET

## 3. Applications

- Continuous Current Mode (CCM) Power Factor Correction (PFC)
- Half-bridge/full-bridge switched-mode power supplies
- Half-bridge lighting ballasts

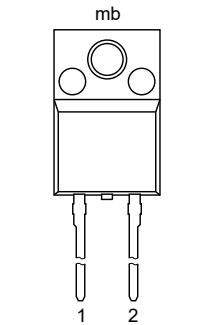
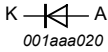
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I <sub>F(AV)</sub>	average forward current	δ = 0.5 ; T <sub>h</sub> ≤ 59 °C; square-wave pulse; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a>		-	-	8	A
I <sub>FRM</sub>	repetitive peak forward current	δ = 0.5 ; t <sub>p</sub> = 25 μs; T <sub>h</sub> ≤ 59 °C; square-wave pulse		-	-	16	A
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 10 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse		-	-	80	A
		t <sub>p</sub> = 8.3 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse		-	-	88	A
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 8 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 4</a>		-	1.4	1.85	V
		I <sub>F</sub> = 8 A; T <sub>j</sub> = 25 °C		-	2	2.9	V
		I <sub>F</sub> = 16 A; T <sub>j</sub> = 150 °C		-	1.7	2.3	V
Dynamic characteristics							
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 8 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>j</sub> = 100 °C		-	32	40	ns
		I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 50 A/μs; T <sub>j</sub> = 25 °C		-	30	52	ns
		I <sub>F</sub> = 8 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 5</a>		-	19	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-220F (SOD113)</p>	
2	A	anode		
mb	n.c.	mounting base; isolated		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYC8X-600	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 2-lead TO-220 "full pack"	SOD113

7. Marking

Table 4. Marking codes

Type number	Marking code
BYT79X-600P	BYT79X-600P

8. Limiting values

Table 5. Limiting values  
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>RRM</sub>	repetitive peak reverse voltage		-	600	V
V <sub>RWM</sub>	crest working reverse voltage		-	600	V
I <sub>F(AV)</sub>	average forward current	δ = 0.5 ; T <sub>h</sub> ≤ 59 °C; square-wave pulse; Fig. 1; Fig. 2	-	8	A
I <sub>FRM</sub>	repetitive peak forward current	δ = 0.5 ; t <sub>p</sub> = 25 μs; T <sub>h</sub> ≤ 59 °C; square-wave pulse	-	16	A
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 10 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse	-	80	A
		t <sub>p</sub> = 8.3 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse	-	88	A
T <sub>stg</sub>	storage temperature		-40	150	°C
T <sub>j</sub>	junction temperature		-	150	°C

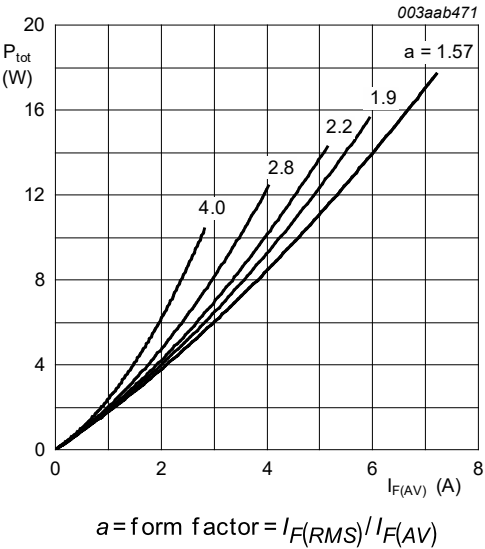


Fig. 1. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

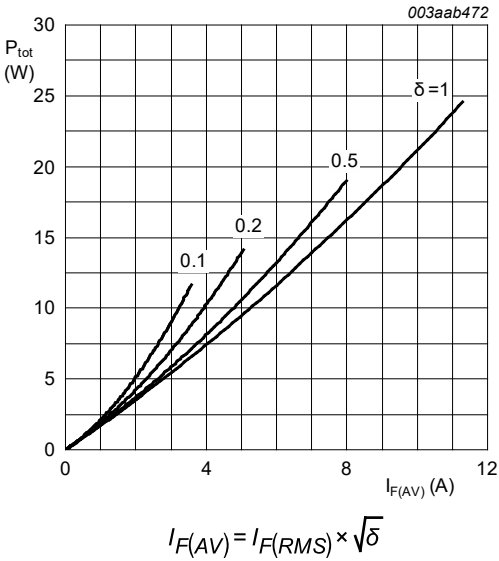


Fig. 2. Forward power dissipation as a function of average forward current; square wave waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to heatsink	with heatsink compound; Fig. 3	-	-	4.8	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air		-	55	-	K/W

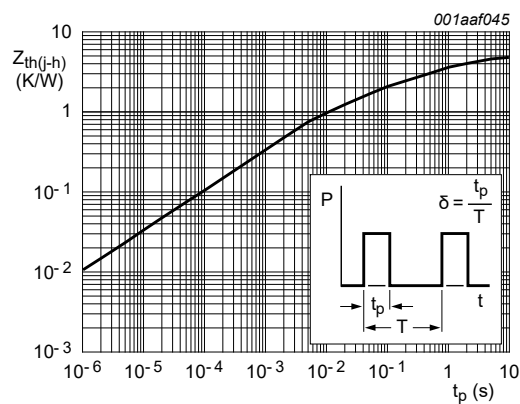


Fig. 3. Transient thermal impedance from junction to heatsink as a function of pulse width

10. Isolation characteristics

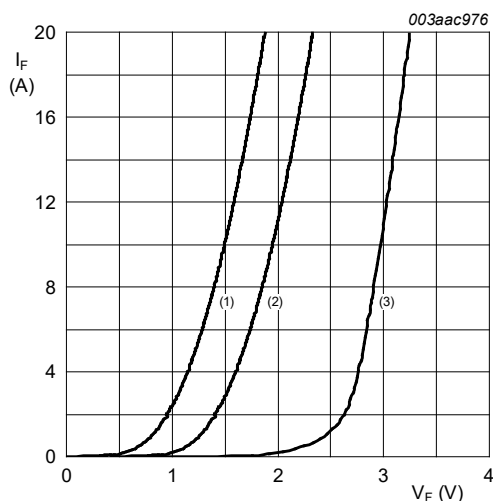
Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
$C_{isol}$	isolation capacitance	from cathode to external heatsink	-	10	-	pF

## 11. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 8 A; T <sub>J</sub> = 150 °C; <a href="#">Fig. 4</a>		-	1.4	1.85	V
		I <sub>F</sub> = 8 A; T <sub>J</sub> = 25 °C		-	2	2.9	V
		I <sub>F</sub> = 16 A; T <sub>J</sub> = 150 °C		-	1.7	2.3	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 500 V; T <sub>J</sub> = 100 °C		-	1.1	3	mA
		V <sub>R</sub> = 600 V; T <sub>J</sub> = 25 °C		-	9	150	μA
Dynamic characteristics							
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 8 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>J</sub> = 100 °C		-	32	40	ns
		I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 50 A/μs; T <sub>J</sub> = 25 °C		-	30	52	ns
		I <sub>F</sub> = 8 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>J</sub> = 25 °C; <a href="#">Fig. 5</a>		-	19	-	ns
I <sub>RM</sub>	peak reverse recovery current	I <sub>F</sub> = 10 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>J</sub> = 100 °C		-	9.5	12	A
		I <sub>F</sub> = 8 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 50 A/μs; T <sub>J</sub> = 125 °C		-	1.5	5.5	A
Q <sub>r</sub>	recovered charge	I <sub>F</sub> = 1 A; V <sub>R</sub> = 100 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>J</sub> = 25 °C		-	12	-	nC
V <sub>FR</sub>	forward recovery voltage	I <sub>F</sub> = 10 A; dI <sub>F</sub> /dt = 100 A/μs; T <sub>J</sub> = 25 °C; <a href="#">Fig. 6</a>		-	8	10	V



- (1)  $T_J = 150 \text{ }^\circ\text{C}$ ; typical values  
 (2)  $T_J = 150 \text{ }^\circ\text{C}$ ; maximum values  
 (3)  $T_J = 25 \text{ }^\circ\text{C}$ ; maximum values

Fig. 4. Forward current as a function of forward voltage

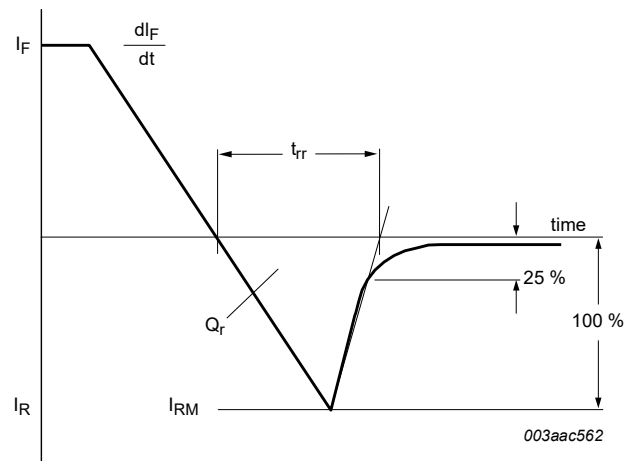


Fig. 5. Reverse recovery definitions; ramp recovery

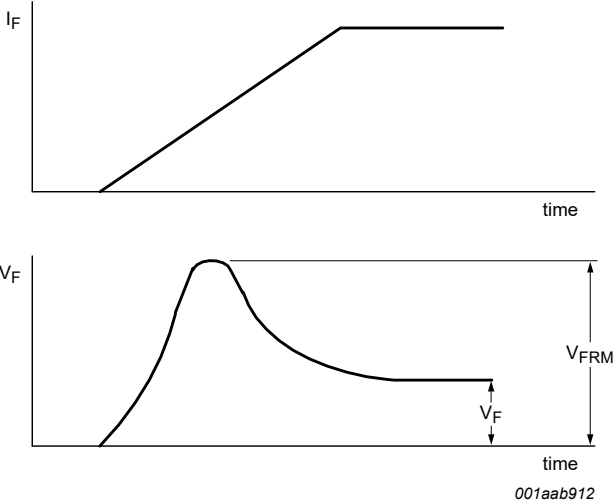
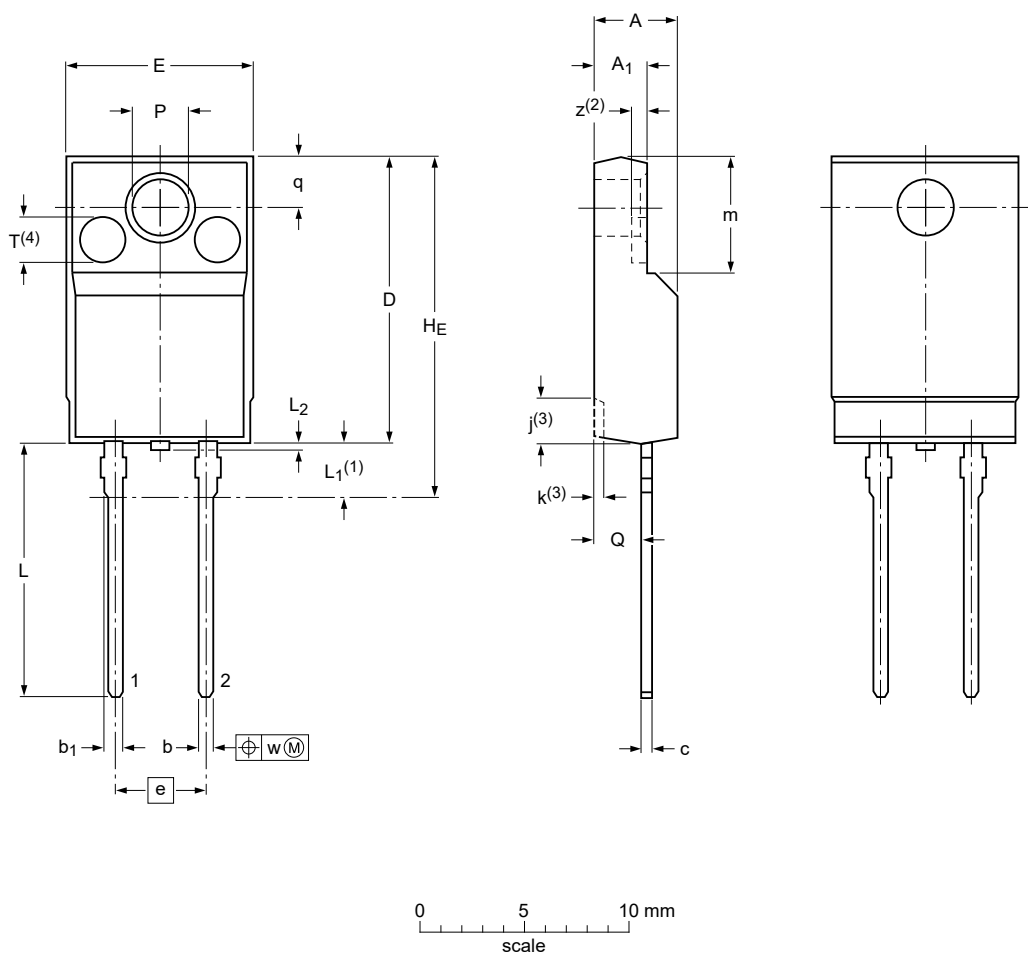


Fig. 6. Forward recovery definitions

12. Package outline

Plastic single-ended package; isolated heatsink mounted;  
1 mounting hole; 2-lead TO-220 'full pack'

SOD113



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	b <sub>1</sub>	c	D	E	e	H <sub>E</sub> max	j(3)	k(3)	L	L <sub>1</sub> (1)	L <sub>2</sub> max	m	P	Q	q	T <sup>(4)</sup>	w	z <sup>(2)</sup>
mm	max	4.6	2.9	0.9	1.1	0.7	15.8	10.3		2.7	0.6	14.4	3.3		6.5	3.2	2.6				
	nom							5.08	19.0					0.5				2.6	2.55	0.4	0.8
	min	4.0	2.5	0.7	0.9	0.4	15.2	9.7		1.7	0.4	13.5	2.8		6.3	3.0	2.3				

- Notes
- 1. Terminals are uncontrolled within zone L1.
  - 2. z is depth of T.
  - 3. Dot lines area designs may vary.
  - 4. Eject pin mark is for reference only.

sod113\_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOD113		2-lead TO-220F				-07-06-08- 15-08-28

Fig. 7. Package outline TO-220F (SOD113)

## 13. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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